UNISONIC TECHNOLOGIES CO., LTD

3N80Z **Power MOSFET**

3.0A, 800V N-CHANNEL **POWER MOSFET**

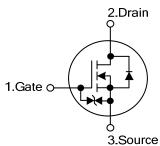
DESCRIPTION

The UTC 3N80Z provide excellent $R_{DS(ON)}$, low gate charge and operation with low gate voltages. This device is suitable for use as a load switch or in PWM applications.

FEATURES

- * Fast Switching Capability



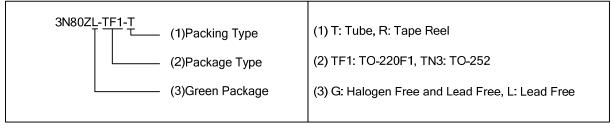


TO-220F1 * $R_{DS(ON)}$ < 4.2 Ω @ V_{GS} =10V, I_D =1.5A * Ultra Low Gate Charge (typical 19 nC) TO-252 * Low Reverse Transfer Capacitance (C_{RSS} = Typical 11 pF) * Avalanche Energy Specified * Improved dv/dt Capability, High Ruggedness **SYMBOL**

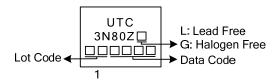
ORDERING INFORMATION

Ordering Number		Dookago	Pin	Assignm	Dooking		
Lead Free	Halogen Free	Package	1	2	3	Packing	
3N80ZL-TF1-T	3N80ZG-TF1-T	TO-220F1	G	D	S	Tube	
3N80ZL-TN3-R	3N80ZG-TN3-R	TO-252	G	D	S	Tape Reel	

Pin Assignment: G: Gate D: Drain S: Source



MARKING



www.unisonic.com.tw 1 of 6

■ **ABSOLUTE MAXIMUM RATINGS** (T_C=25°C, unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT	
Drain-Source Voltage (V _{GS} =0V)	V _{DSS}	800	V	
Drain-Gate Voltage (R _G =20kΩ)	V_{DGR}	800	V	
Gate-Source Voltage	V _{GSS}	±20	V	
Gate-Source Breakdown Voltage (I _{GS} =±1mA)	BV _{GSO}	30 (MIN)	V	
Insulation Withstand Voltage (DC)	V _{ISO}	2500	V	
Continuous Drain Current	I _D	3.0	А	
Pulsed Drain Current	I _{DM}	12	Α	
Avalanche Current (Note 2)	I _{AR}	4.0	Α	
Single Pulse Avalanche Energy (Note 3)	E _{AS}	80	mJ	
Peak Diode Recovery dv/dt (Note 4)	dv/dt	3.5	V/ns	
TO-220F1	0	25	W	
Power Dissipation TO-252	P _D	50	W	
Junction Temperature	T_J	+150	°C	
Storage Temperature	T _{STG}	-55 ~ +150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L=10mH, I_{AS} =4.0A, V_{DD} =50V, R_{G} =25 Ω , Starting T_{J} = 25°C.
- 4. $I_{SD} \le 3.0 \text{A}$, di/dt $\le 200 \text{A}/\mu \text{s}$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25 ^{\circ}\text{C}$

■ THERMAL DATA

PARAMETER		SYMBOL	RATING	UNIT
lunation to Ambient	TO-220F1	0	62.5	°C/W
Junction to Ambient	TO-252	θ_{JA}	110	°C/W
lunation to Case	TO-220F1	0	5.0	°C/W
Junction to Case	TO-252	$\theta_{ m JC}$	2.5	°C/W

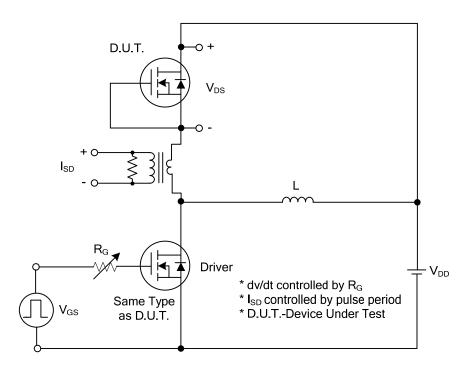
■ **ELECTRICAL CHARACTERISTICS** (T_J =25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	800			V	
Drain-Source Leakage Current	I _{DSS}	V _{DS} =800V, V _{GS} =0V			1	μΑ	
Gate-Source Leakage Current	I_{GSS}	V _{GS} =±20V, V _{DS} =0V			±10	μΑ	
ON CHARACTERISTICS							
Gate Threshold Voltage	nreshold Voltage $V_{GS(TH)}$ $V_{DS}=V_{GS}$, $I_D=250\mu A$		3.0		4.5	V	
Static Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =1.5A			4.2	Ω	
DYNAMIC CHARACTERISTICS							
Input Capacitance	C _{ISS}			485		pF	
Output Capacitance	Coss	V_{GS} =0V, V_{DS} =25V, f=1MHz		57		pF	
Reverse Transfer Capacitance	C_{RSS}			11		pF	
SWITCHING CHARACTERISTICS			_				
Total Gate Charge	Q_G	-V _{DS} =50V, V _{GS} =10V, I _D =1.3A, -I _G =250μA (Note 1, 2)		68		nC	
Gate to Source Charge	Q_GS			6.0		nC	
Gate to Drain Charge	Q_GD			9.5		nC	
Turn-ON Delay Time	t _{D(ON)}			55		ns	
Rise Time	t_R	$V_{DD} = 30V, V_{GS} = 10V, I_D = 0.5A,$		52		ns	
Turn-OFF Delay Time	t _{D(OFF)}	R _G =25Ω (Note 1, 2)		170		ns	
Fall-Time	t _F			42		ns	
SOURCE- DRAIN DIODE RATINGS AND CHA	ARACTERIS	TICS					
Maximum Body-Diode Continuous Current	I_{SD}				3.0	Α	
Maximum Body-Diode Pulsed Current	I _{SDM}				12	Α	
Drain-Source Diode Forward Voltage	V_{SD}	I _S =3.0A ,V _{GS} =0V			1.6	V	
Reverse Recovery Time	t _{rr}	I _S =3.0A, V _{GS} =0V,		480		ns	
Reverse Recovery Charge	Q_{rr}	di _F /dt=100A/µs		2.7		μC	

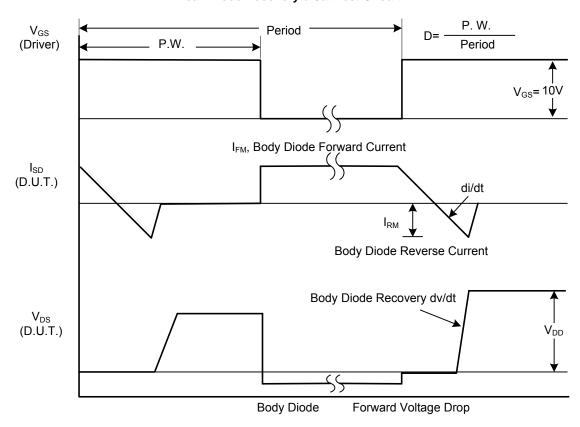
Notes: 1. Pulse width=300µs, Duty cycle ≤1.5%

^{2.} $C_{OSS(EQ)}$ is defined as constant equivalent capacitance giving the same charging time as C_{OSS} when V_{DS} increases from 0to 80% V_{DSS} .

■ TEST CIRCUITS AND WAVEFORMS

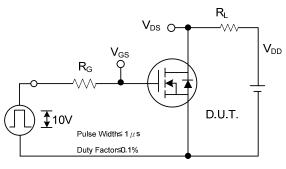


Peak Diode Recovery dv/dt Test Circuit

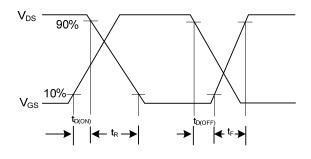


Peak Diode Recovery dv/dt Waveforms

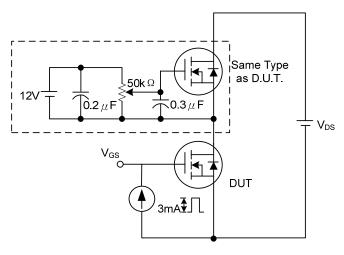
■ TEST CIRCUITS AND WAVEFORMS (Cont.)



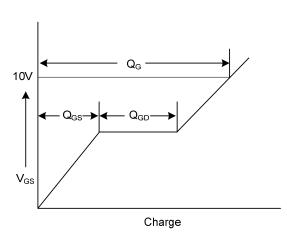
Switching Test Circuit



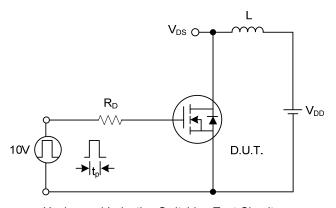
Switching Waveforms



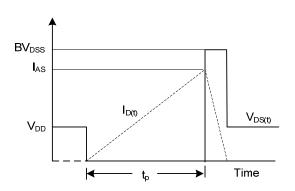
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

UTC assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all UTC products described or contained herein. UTC products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice.